

LNJ115W8VRA

Surface Mounting Chip LED

TSS-2 Type

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

- Pure Green

Parameter	Symbol	Rating	Unit
Power dissipation	P_D	40	mW
Forward current	I_F	10	mA
Pulse forward current *	I_{FP}	50	mA
Reverse voltage	V_R	5	V
Operating ambient temperature	T_{opr}	-30 to +85	$^\circ\text{C}$
Storage temperature	T_{stg}	-40 to +100	$^\circ\text{C}$

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.**■ Lighting Color**

- Pure Green
- Soft Orange

- Soft Orange

Parameter	Symbol	Rating	Unit
Power dissipation	P_D	55	mW
Forward current	I_F	20	mA
Pulse forward current *	I_{FP}	60	mA
Reverse voltage	V_R	4	V
Operating ambient temperature	T_{opr}	-30 to +85	$^\circ\text{C}$
Storage temperature	T_{stg}	-40 to +100	$^\circ\text{C}$

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.**■ Electro-Optical Characteristics** $T_a = 25^\circ\text{C}$

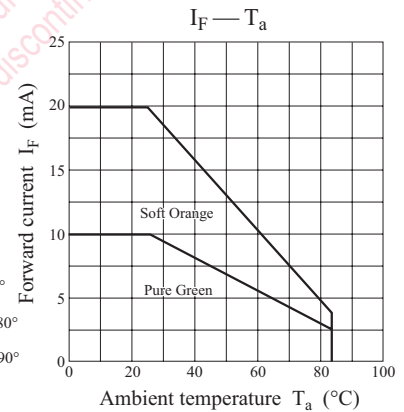
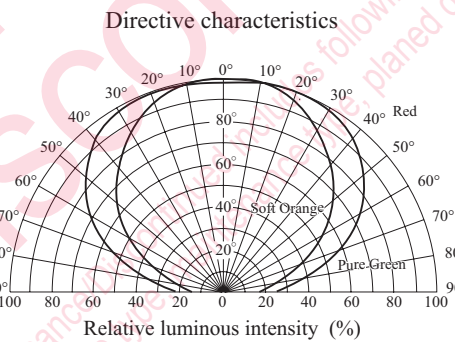
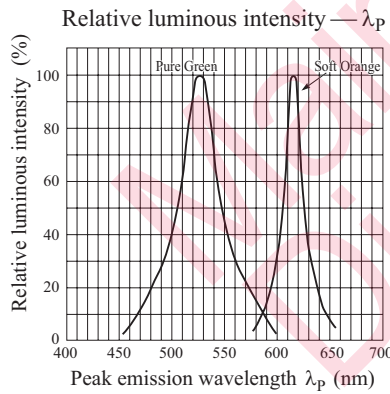
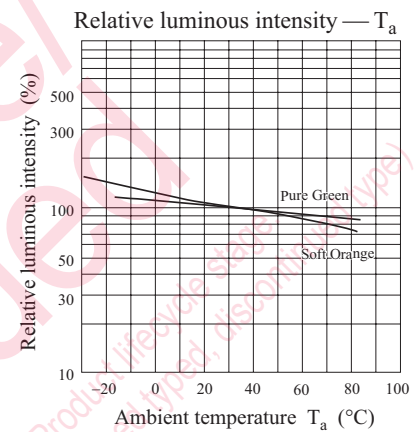
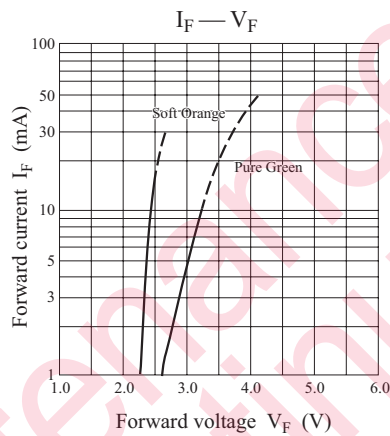
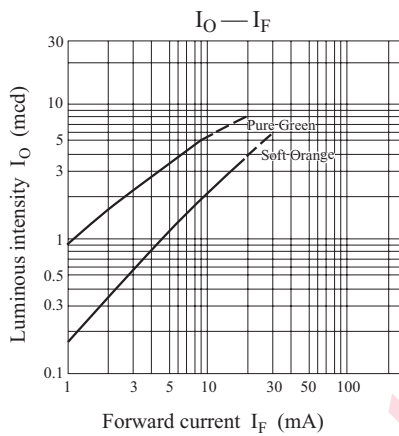
- Pure Green

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity	I_O	$I_F = 5\text{ mA}$	10.3	34		mc
Reverse current	I_R	$V_R = 5\text{ V}$			10	μA
Forward voltage	V_F	$I_F = 5\text{ mA}$		3.0	3.7	V
Peak emission wavelength	λ_p	$I_F = 5\text{ mA}$		525		nm
Spectral half band width	$\Delta\lambda$	$I_F = 5\text{ mA}$		45		nm

■ Electro-Optical Characteristics (Continued) $T_a = 25^\circ\text{C}$

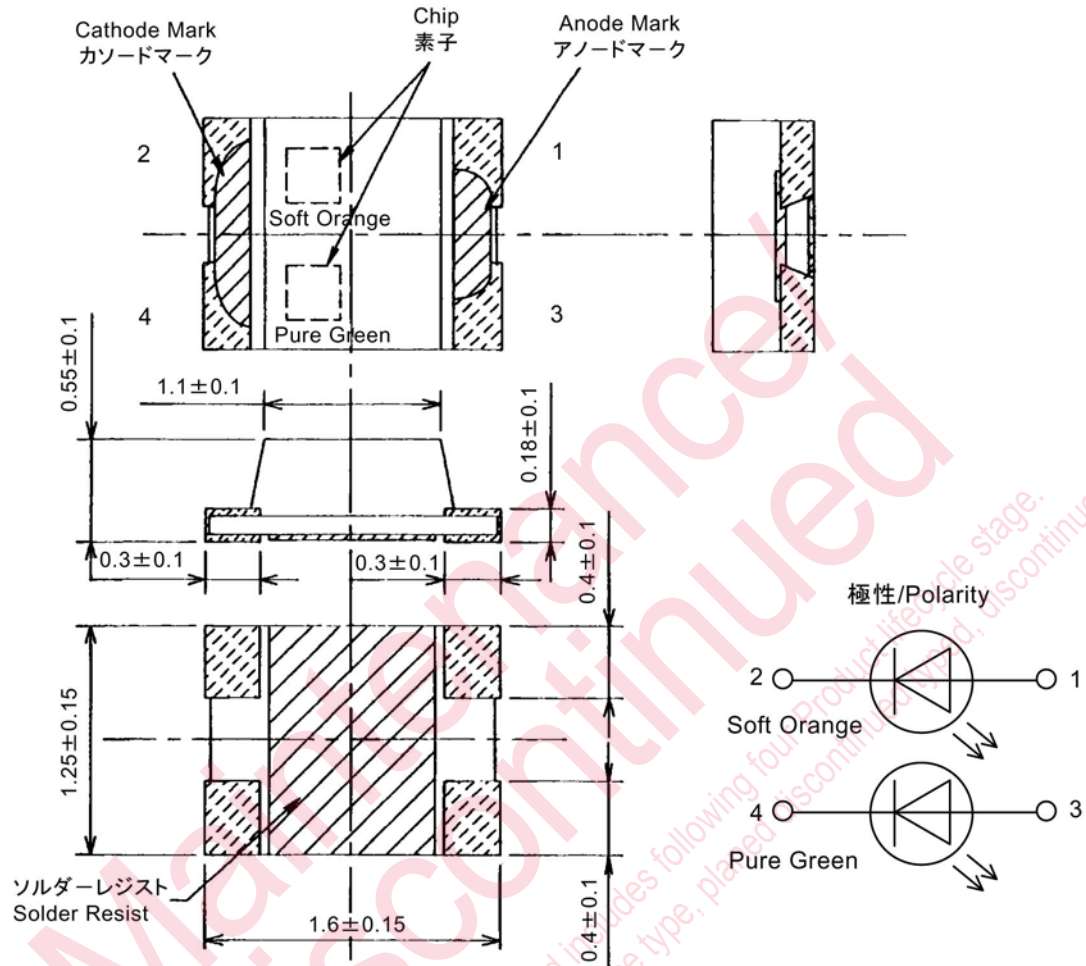
• Soft Orange

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity	I_O	$I_F = 10\text{ mA}$	7	23		mcd
Reverse current	I_R	$V_R = 4\text{ V}$			100	μA
Forward voltage	V_F	$I_F = 10\text{ mA}$		1.95	2.5	V
Peak emission wavelength	λ_P	$I_F = 10\text{ mA}$		615		nm
Spectral half band width	$\Delta\lambda$	$I_F = 10\text{ mA}$		20		nm



■ Package (Unit: mm)

KLTFTN4K1540



• Pin name

- 1, 3: Anode
- 2, 4: Cathode

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